TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

T6C24

ROW DRIVER LSI FOR A DOT MATRIX LCD

The T6C24 is a row (common) driver LSI for a dot matrix LCD. The T6C24 generates the timing signals for the display using a built-in oscillator and also controls the T6C23 column (segment) LCD driver.

The T6C24 features a low-impedance 240-output row driver. The T6C24 also includes internal resistors to divide the bias voltage, a power supply op-amp and a contrast control circuit. The T6C24 can be used in conjunction with the T6C23 to construct a low-power LCD system.

Features

- Dot matrix graphic LCD row driver
- Built-in oscillator (additional external resistor)
- Duty : 1/240
- Display OFF function : /DSPOF = L, all LCD outputs = VSS
- Low power consumption
- Logic power supply : 2.7 to 5.5 V
- LCD power supply : 8.0 V to 30.0 V
- CMOS process
- Package : TCP (Tape Carrier Package)

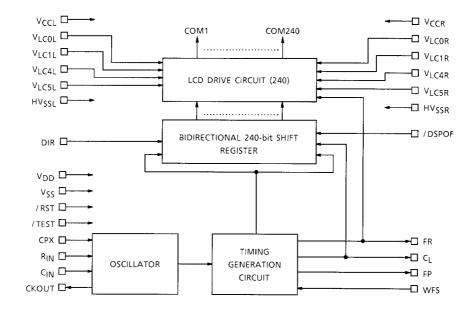
	ι	Jnit: mm		
т6С24	LEAD PITCH			
10024	IN	OUT		
(UAW)	1.2	0.22		
(UBW)	1.2	0.21		
(UFW, 6FS)	1.2	0.21		

Please contact Toshiba or on authorized Toshiba dealer for information on package dimensions.

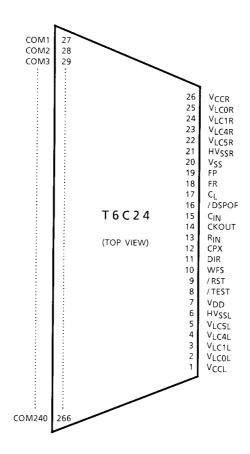
TCP (Tape Carrier Package)

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Block Diagram







Note: The above diagram shows the pin configuration of the LSI chip; it does not show the configuration of the tape carrier package.

Pin Functions

Pin Name	Pin No.	1/0	Functions		
COM1 to COM240	27 to 266	Output	Row driver outputs		
CL	17	Output	Shift clock pulse		
FP	19	Output	Display synchronous signal		
FR	18	Output	Frame signal		
DIR	11	Input	Data flow direction select. Usually connected to V_{DD} DIRDATA FLOWHCOM1 \rightarrow COM240LCOM240 \rightarrow COM1		
WFS	10	Input	Frame signal inversion select. Usually connected to V _{DD} . WFS = H: FR phase change per 13 lines. WFS = L: FR phase change per 17 lines.		
/ DSPOF	16	Input	Display off. Usually connected to V _{DD} / DSPOF = H: Display-on mode, (COM1 to COM240) are operational. / DSPOF = L: Display-off mode, (COM1 to COM240) are at the V _{SS} level.		
/ RST	9	Input	/ RST = L: Reset state. Usually connected to V _{DD}		
СРХ	12	Input	Crystal oscillation / CR oscillation Select CPX = L : CR oscillation CPX = H: Crystal oscillation or external clock input from C _{IN}		
R _{IN}	13	Input	Connected to resistor for built-in oscillator		
C _{IN}	15	Input	Connected to crystal		
CKOUT	14	Output	Connected to resistor or crystal for built-in oscillator		
/ TEST	8	Input	Test pin. Usually connected to V _{DD}		
V _{DD} , V _{SS}	7, 20	—	Power supply		
V _{CCL} , V _{CCR} V _{LC0L} , V _{LC0R} V _{LC1L} , V _{LC1R} V _{LC4L} , V _{LC4R} V _{LC5L} , V _{LC5R} HV _{SSL} , HV _{SSR}	1, 26 2, 25 3, 24 4, 23 5, 22 6, 21	_	Power supply for LCD drive		

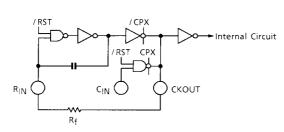
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Function of Each Block

• Oscillator

The T6C24 has an on-chip oscillator (an external resistor is required).

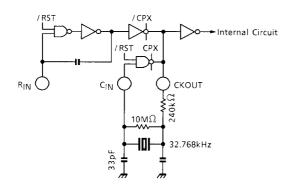
(1) CPX = L



R _f	f _{osc}		
390 kΩ	54 kHz		
620 kΩ	34 kHz		
780 kΩ	27 kHz		

Note: The resistor values are typical values. The oscillation frequency depends on how the device has been mounted. Hence R_f must be adjusted to achieve the target oscillation frequency.

(2) CPX = H



• Timing generation circuit

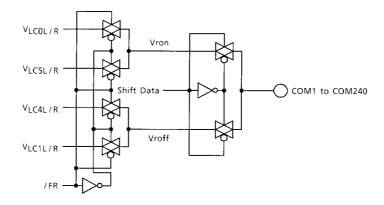
This circuit divides the oscillator frequency and generates the display timing signals (CL, FP and FR).

• Shift register

 $240 \hbox{-} bit \ shift \ register$

• Row driver circuit and LCD voltage generation circuit

The T6C24 has 240 row drivers and four different LCD drive output voltage levels. The display data from the latch circuit and the M signal determine which of the four LCD drive voltage is selected. The voltage generation circuit and row driver circuit are shown in the following diagram.



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Rating	Unit
Supply Voltage (1)	V _{DD} (Note 2)	-0.3 to 7.0	V
Supply Voltage (2)	(Note 1, 2)	-0.3 to 32.0	V
Input Voltage	V _{in} (Note 2, 3)	-0.3 to V _{DD} + 0.3	V
Operating Temperature	T _{opr}	-20 to 75	°C
Storage Temperature	T _{stg}	−55 to 125	°C

Note 1: V_{CCL}, V_{CCR}, V_{LC0L}, V_{LC0R}, V_{LC1L}, V_{LC1R}, V_{LC4L}, V_{LC4R}, V_{LC5L} and V_{LC5R}

Note 2: Referenced to $V_{SS},\,HV_{SSL}$ and HV_{SSR}

Note 3: Applies to all data bus and I / O pins.

Note 4: Ensure that the following condition is always maintained. $V_{CCL / R} \ge V_{LC0L / R} \ge V_{LC1L / R} \ge V_{LC4L / R} \ge V_{LC5L / R} \ge HV_{SSL / R}$

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Electrical Characteristics DC Characteristics Test Conditions (1) (Unless Otherwise Noted, V

Unless Otherwise Noted,	V _{SS} = 0 V, V _{DD} = 3.0 V ± 10%, V _{CCL / R} = 23.0 V ± 10%	,, <i>\</i>
	Ta = −20 to 75°C	J

Ite	em	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit	Pin Name
Operating	Supply (1)	V _{DD}	-	—	2.7	_	3.3	V	V _{DD}
Operating	Supply (2)	V _{CC}	—	_	8.0	—	30.0	V	V _{CCL} , V _{CCR}
Input	H Level	V _{IH}	_		0.7 V _{DD}	_	V_{DD}	V	WFS, CPX, DIR, / DSPOF, / RST,
Voltage	L Level	V _{IL}	_		0	_	0.3 V _{DD}	V	/ TEST
Output	H Level	V _{OH}	_	I _{OH} = -400 μA	V _{DD} - 0.4	_		V	C _L , FP, FR
Voltage	L Level	V _{OL}	-	I _{OL} = 400 μA	V_{SS}	_	V _{SS} +0.4	V	Ο _L , ΓΓ, ΓΚ
Row Drive Resistance		Rrow	_	(Note 5) Load voltage = output level of 0.5 V	_	_	1.5	kΩ	COM1 to COM240
Input Leak	age	IIL	_	V _{IN} = V _{DD} to GND	-1	_	1	μA	WFS, CPX, DIR, / DSPOF, / RST, / TEST
Current Co (1)	onsumption	I _{SS}	_	(Note 1)	_	-35	-50	μA	V _{DD}
Current Co (2)	onsumption	ICC	_	(Note 2)	_	10	20	μA	V _{CCL} , V _{CCR} V _{LC0L} , V _{LC0R}
Current Co (3)	onsumption	IDOF	-	(Note 3)		25	40	μA	V _{SS} , V _{SSL} , V _{SSR} V _{LC5L} , V _{LC5R}
Current Co (4)	onsumption	I _{STB}	-	(Note 4)	-1	_	1	μA	V _{SS} , V _{SSL} , V _{SSR} V _{LC5L} , V _{LC5R}
Operating	Freq.	f _{osc}	_	—	20	_	100	kHz	R _{IN} , C _{IN}
External C Frequency		f _{ex}	_	—	20	_	100	kHz	C _{IN}
External C	lock Duty	f _{duty}	_	—	40	50	60	%	C _{IN}
External C Fall Time	lock Rise /	t _r / t _f	—	_	_	—	50	ns	C _{IN}

Note 1: Logic current : $V_{DD} = 3.0 V \pm 10\%$, Ta = 25°C, R_f = 620 k Ω (33.6 kHz), no load Note 2: LCD driver current : $V_{DD} = 3.0 V \pm 10\%$, $V_{CCL / R} = 23.0 V$, Ta = 25°C, 1 / 13 bias, R_f = 620 k Ω , no load

Note 3: Display-off current : $V_{DD} = 3.0 \text{ V} \pm 10\%$, $V_{CCL / R} = 23.0 \text{ V}$, Ta = 25°C, 1 / 13 bias, R_f = 620 kΩ, / DSPOF = L, no load Note 4: Standby current : $V_{DD} = 3.0 \text{ V} \pm 10\%$, $V_{CCL / R} = 23.0 \text{ V}$, Ta = 25°C, 1 / 13 bias,

Note 4: Standby current $V_{DD} = 3.0 \text{ V} \pm 10\%, \text{ V}_{CCL / R} = 23.0 \text{ V}, \text{ Ta} = 25 \text{ C}, 1 / 13 \text{ blas},$ $R_f = 620 \text{ k}\Omega, / \text{RST} = \text{L}, \text{ no load}$

Note 5: $V_{CCL / R} = V_{LC0L / R} = 23.0 \text{ V}, V_{LC1L / R} = V_{CC} \times 12 / 13, V_{LC4L / R} = V_{CC} \times 1 / 13, HV_{SSL / R} = V_{LC5L / R} = 0 \text{ V}$

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Test Conditions (2)

(Unless Otherwise Noted, $V_{SS} = 0 V$, $V_{DD} = 5.0 V \pm 10\%$, $V_{CCL/R} = 23.0 V \pm 10\%$, Ta = -20 to 75°C

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Itom Symbol		Test Circuit	Test Condition	Min	Тур.	Max	Unit	Pin Name	
Operating	Supply (1)	V _{DD}	—	—	4.5	_	5.5	V	V _{DD}
Operating	Supply (2)	V _{CC}	_	—	8.0		30.0	V	V _{CCL} , V _{CCR}
Input	H Level	V _{IH}	-	—	0.7 V _{DD}	-	V _{DD}	V	WFS, CPX, DIR, / DSPOF, / RST,
Voltage	L Level	V _{IH}	_	_	0		0.3 V _{DD}	V	/ TEST
Output	H Level	V _{OH}	_	I _{OH} = −400 μA	V _{DD} - 0.4			V	C _L , FP, FR
Voltage	L Level	V _{OL}	-	I _{OL} = 400 μA	V_{SS}		V _{SS} + 0.4	V	Ο <u></u> , ΓΓ, ΓΚ
Row Driver Output Resistance		Rrow	-	(Note 5) Load voltage = output level of 0.5 V	-	-	1.5	kΩ	COM1 to COM240
Input Leakage		١ _{IL}	_	V _{IN} = V _{DD} to GND	-1	_	1	μA	WFS, CPX, DIR, / DSPOF, / RST, / TEST
Current Co (1)	onsumption	I _{SS}	-	(Note 1)		-60	-90	μA	V _{DD}
Current Co (2)	onsumption	ICC	-	(Note 2)	_	10	20	μA	V _{CCL} , V _{CCR} V _{LC0L} , V _{LC0R}
Current Consumption (3)		IDOF	-	(Note 3)	_	50	80	μA	V _{SS} , V _{SSL} , V _{SSR} V _{LC5L} , V _{LC5R}
Current Consumption (4)		I _{STB}	-	(Note 4)	-1		1	μA	V _{SS} , V _{SSL} , V _{SSR} V _{LC5L} , V _{LC5R}
Operating Freq.		f _{osc}	—	—	20	_	100	kHz	R _{IN} , C _{IN}
External Clock Frequency		f _{ex}	_	_	20	_	100	kHz	C _{IN}
External Clock Duty		f _{duty}	—	_	40	50	60	%	C _{IN}
External C Fall Time	lock Rise /	t _r / t _f	-	_			50	ns	C _{IN}

Note 5: $V_{CCL / R} = V_{LC0L / R} = 23.0 \text{ V}, V_{LC1L / R} = V_{CC} \times 12 / 13, V_{LC4L / R} = V_{CC} \times 1 / 13, H_{VSSL / R} = V_{LC5L / R} = 0 \text{ V}$

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Handbook" etc..

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